

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.44247	100.0	6.4
			Subtotal	0.44247	100	6.4
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01855	100.0	0.26839
	Pure metal	Aluminium (Al)	7429-90-5	0.448	100.0	6.48
			Subtotal	0.46655	200	6.74839
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.72839	100.0	25
			Subtotal	1.72839	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02323	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05807	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	57.99259	99.86	838.824
			Subtotal	58.07389	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.38332	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.2222	16.0	90
	Filler	Silica fused	60676-86-0	29.16658	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11667	0.3	1.6875
			Subtotal	38.88877	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02	5.0	0.28923
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.14462
	Lead alloy	Lead (Pb)	7439-92-1	0.36993	92.5	5.35077
			Subtotal	0.39993	100	5.78462
			Total	100	100	1446.43301

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